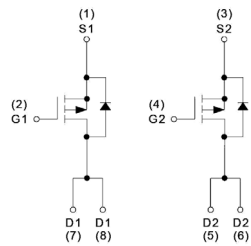


SOP-8 P MOS

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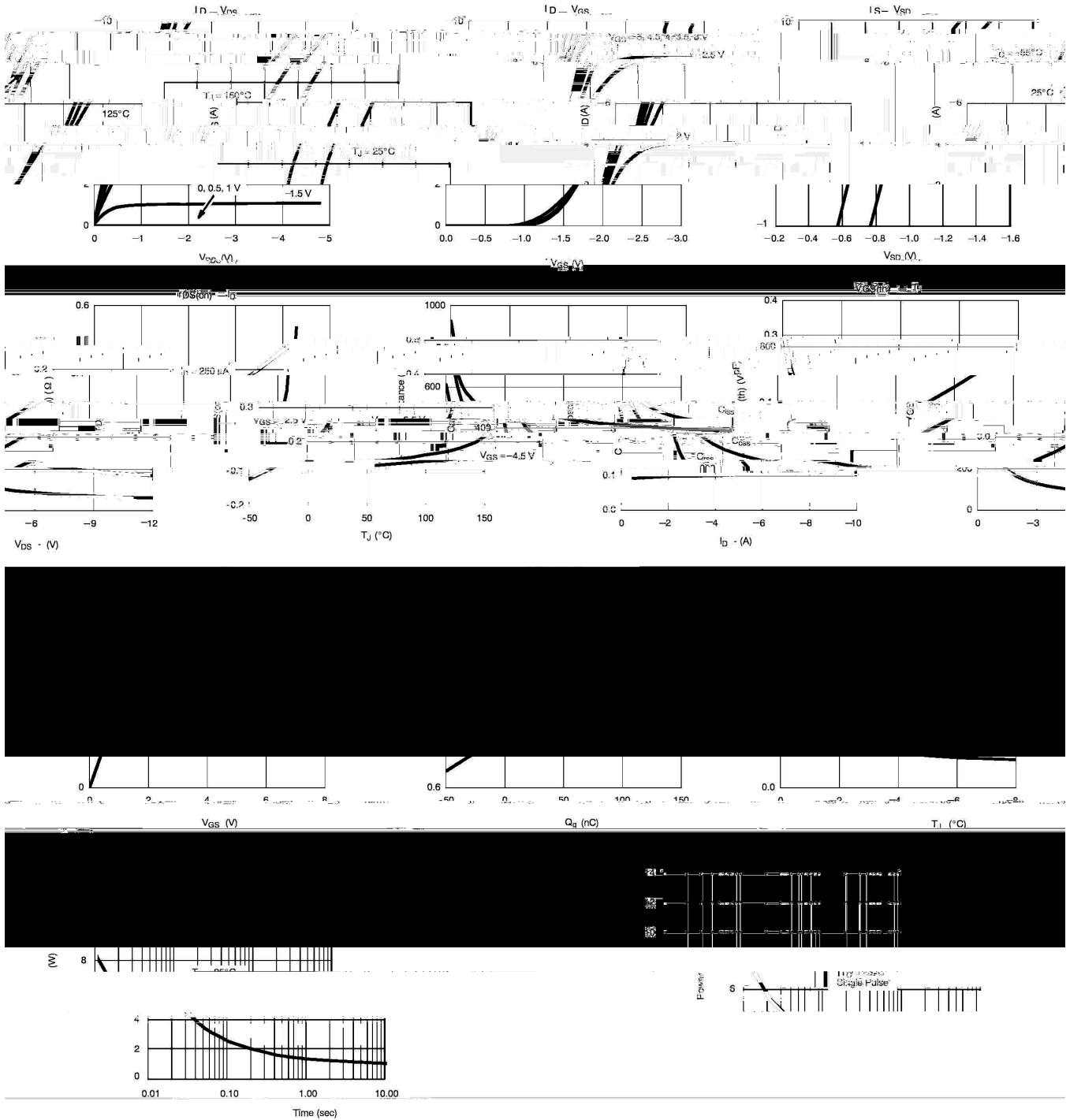


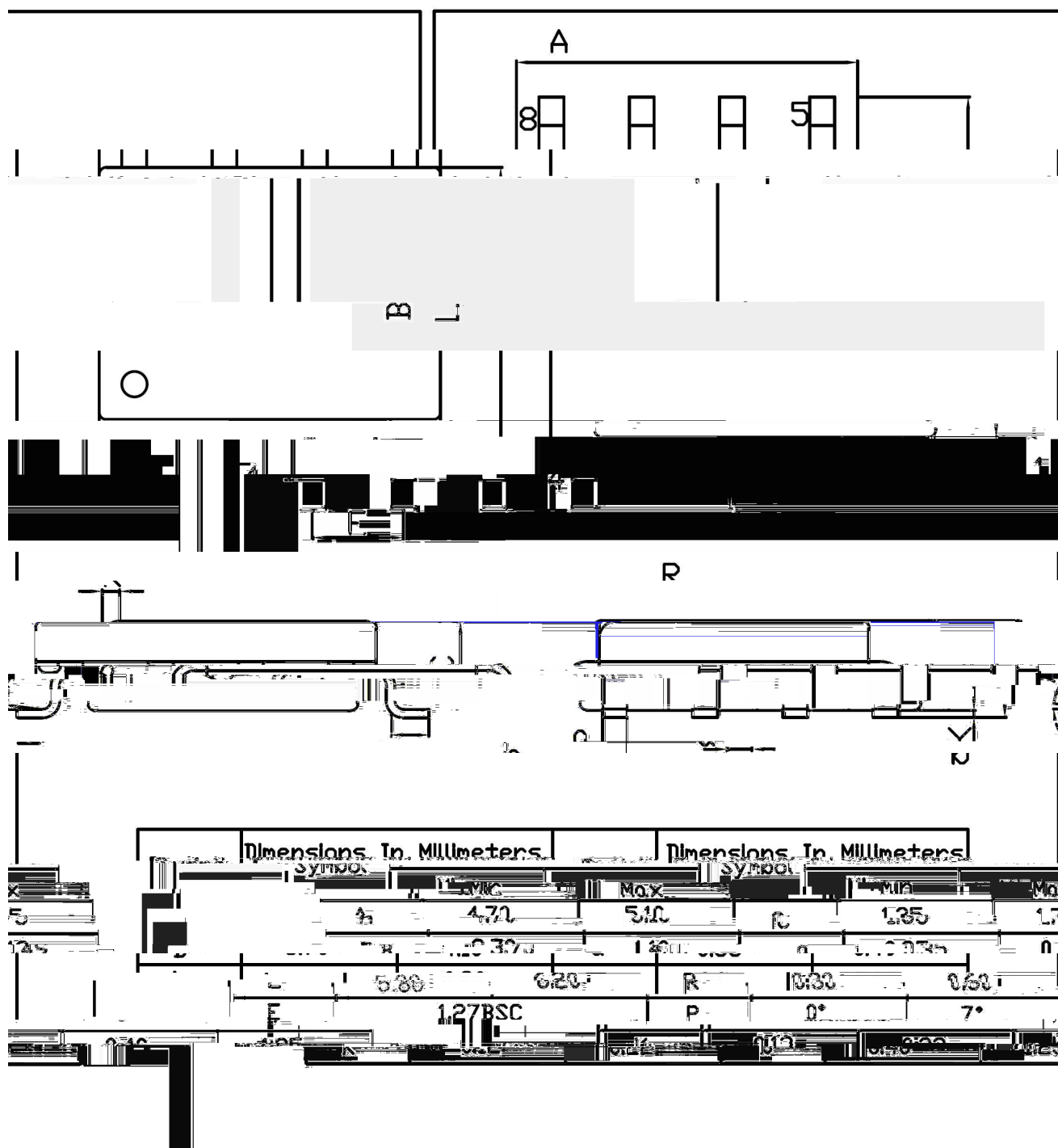
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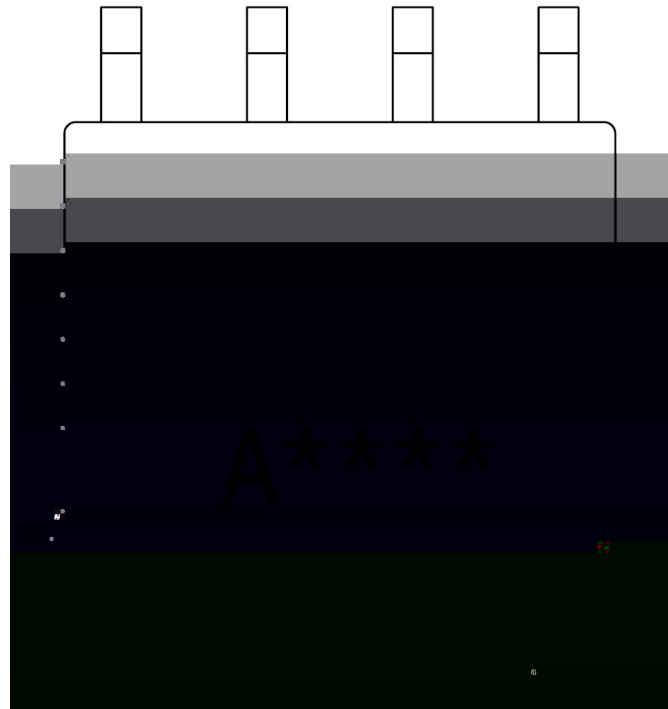


						Ω
		Ω				

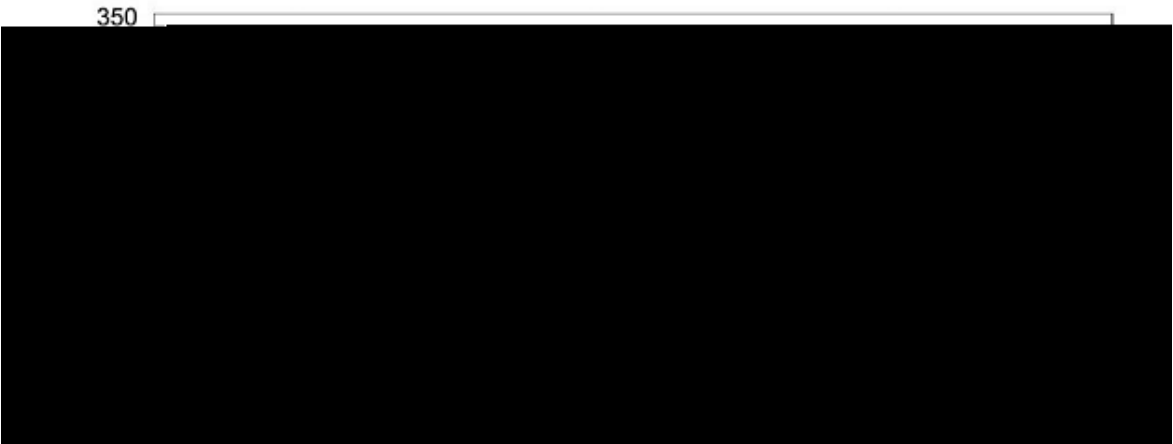
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Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

± ± °C

封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOP/ESOP-8	4,000	2	8,000	6	48,000	13" ×12	360×360×50	380×335×366